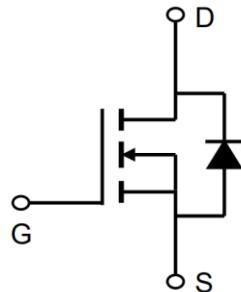


**150V N-Channel Enhancement Mode MOSFET**
**Description**

The 4N15 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 6V. This device is suitable for use as a Battery protection or in other Switching application.

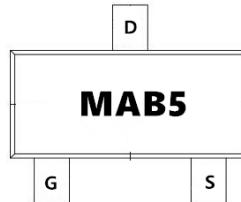

**General Features**

$V_{DS} = 150V$   $I_D = 4A$

$R_{DS(ON)} < 300m\Omega$  @  $V_{GS}=10V$

**Application**

Battery protection



Load switch

Uninterruptible power supply

**Absolute Maximum Ratings ( $T_c=25^{\circ}\text{C}$ unless otherwise noted)**

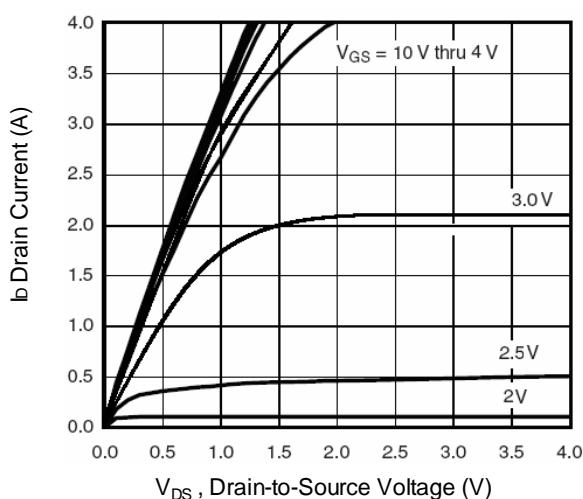
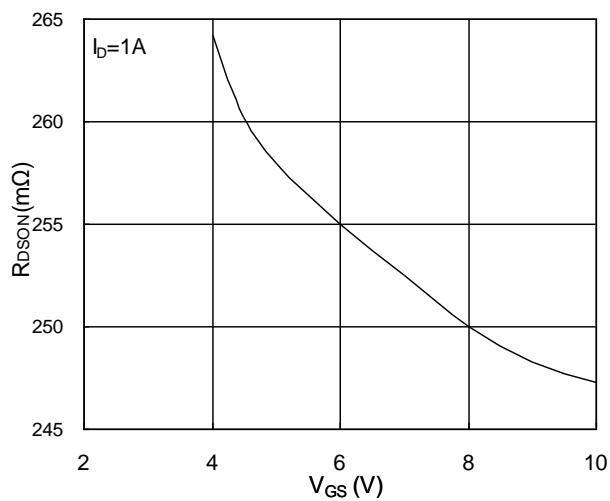
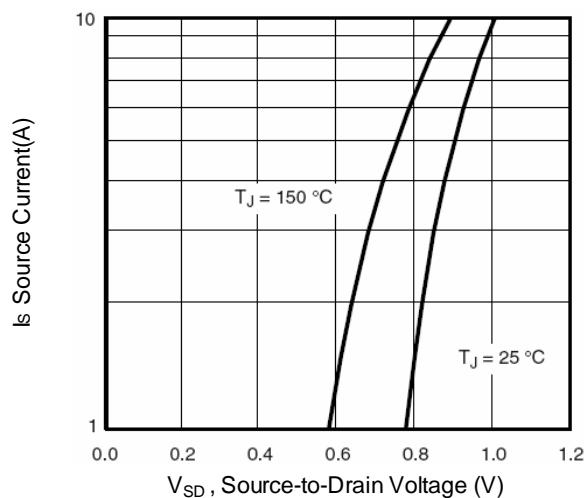
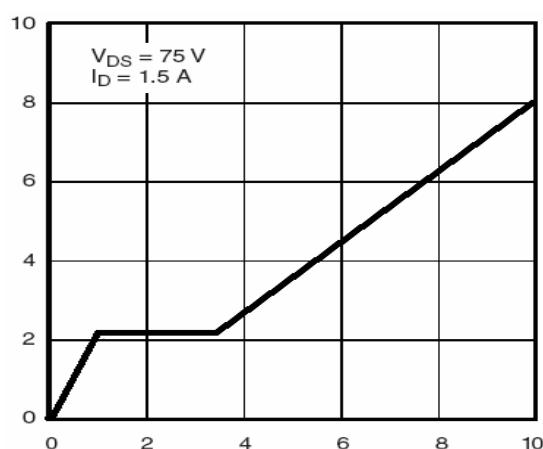
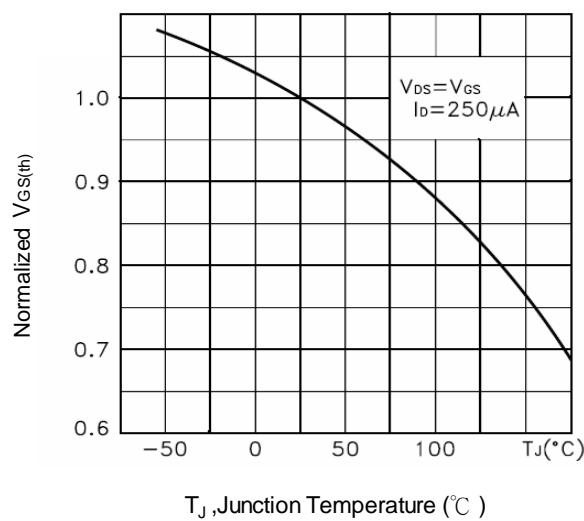
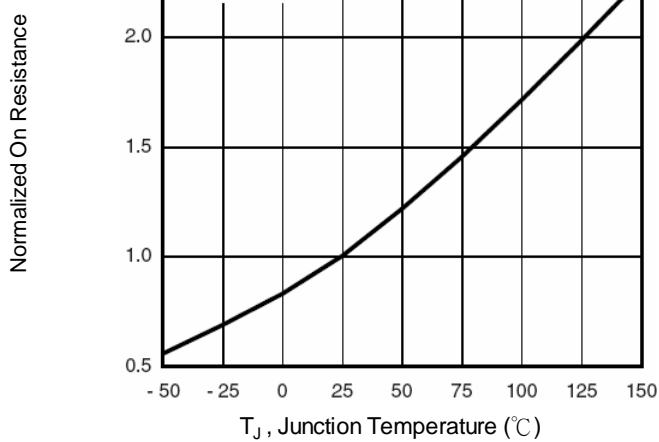
| Symbol                        | Parameter  | Rating     | Units                       |
|-------------------------------|--|------------|-----------------------------|
| $V_{DS}$                      | Drain-Source Voltage                             | 150        | V                           |
| $V_{GS}$                      | Gate-Source Voltage                              | $\pm 20$   | V                           |
| $I_D@T_A=25^{\circ}\text{C}$  | Continuous Drain Current, $V_{GS} @ 10V^1$       | 4          | A                           |
| $I_D@T_A=100^{\circ}\text{C}$ | Continuous Drain Current, $V_{GS} @ 10V^1$       | 1.5        | A                           |
| $I_{DM}$                      | Pulsed Drain Current <sup>2</sup>                | 9          | A                           |
| $P_D@T_A=25^{\circ}\text{C}$  | Total Power Dissipation <sup>3</sup>             | 2          | W                           |
| $T_{STG}$                     | Storage Temperature Range                        | -55 to 150 | $^{\circ}\text{C}$          |
| $T_J$                         | Operating Junction Temperature Range             | -55 to 150 | $^{\circ}\text{C}$          |
| $R_{\theta JA}$               | Thermal Resistance Junction-ambient <sup>1</sup> | 125        | $^{\circ}\text{C}/\text{W}$ |
| $R_{\theta JC}$               | Thermal Resistance Junction-Case <sup>1</sup>    | 80         | $^{\circ}\text{C}/\text{W}$ |

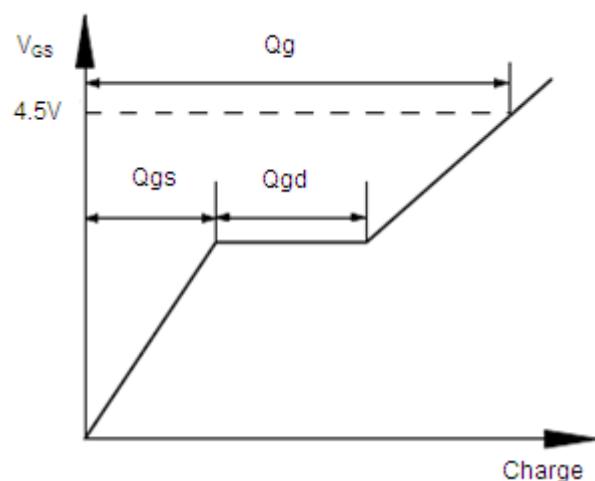
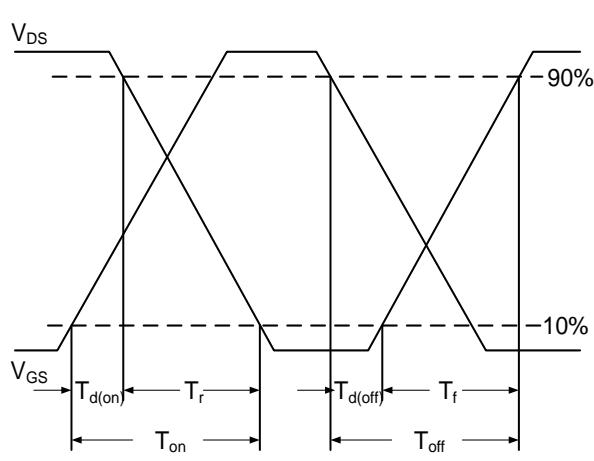
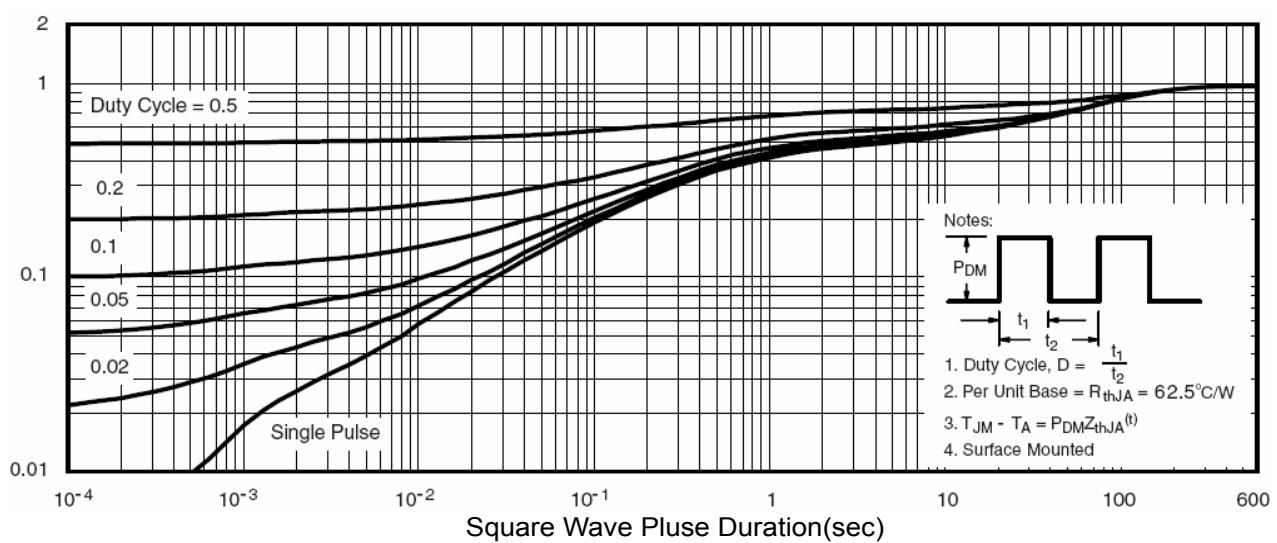
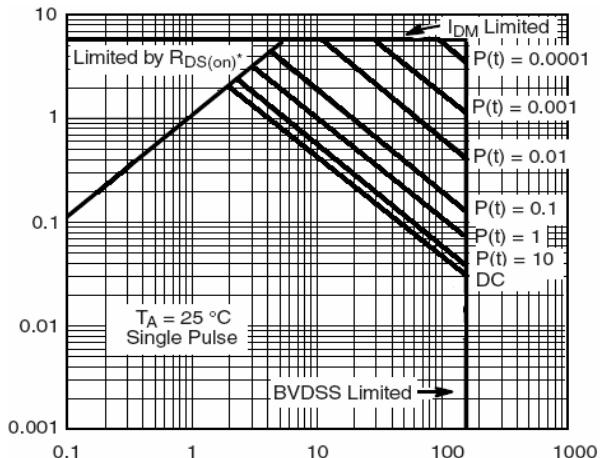
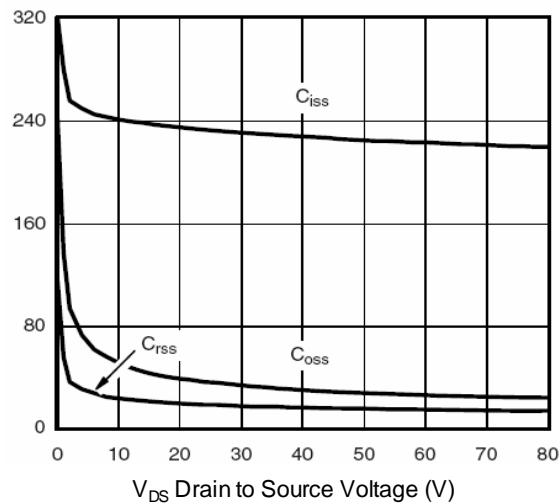
**150V N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

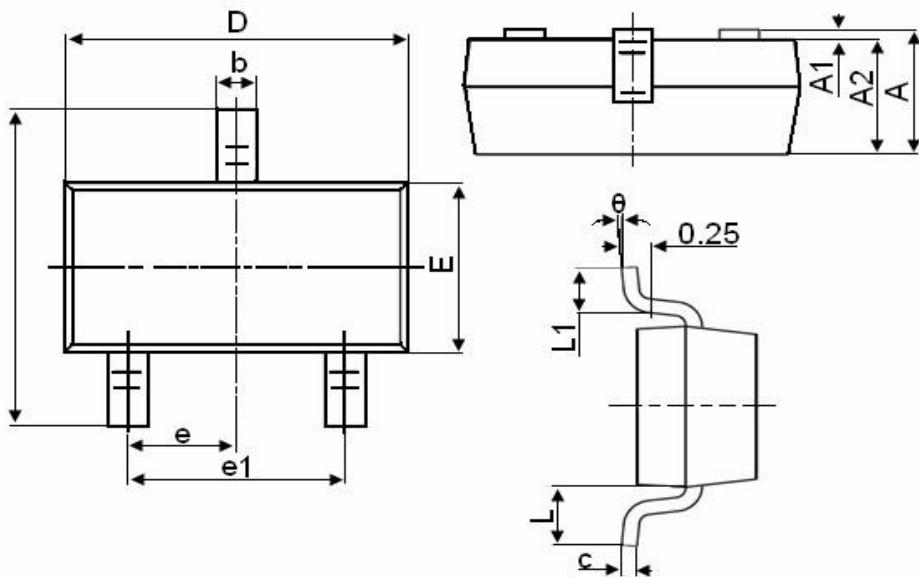
| Symbol                     | Parameter                                 | Condition   | Min | Typ | Max       | Unit             |
|----------------------------|---|---|-----|-----|-----------|------------------|
| $\text{BV}_{\text{DSS}}$   | Drain-Source Breakdown Voltage            | $\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$   | 150 | 165 | -         | V                |
| $\text{I}_{\text{DSS}}$    | Zero Gate Voltage Drain Current           | $\text{V}_{\text{DS}}=150\text{V}, \text{V}_{\text{GS}}=0\text{V}$  | -   | -   | 1         | $\mu\text{A}$    |
| $\text{I}_{\text{GSS}}$    | Gate-Body Leakage Current                 | $\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$   | -   | -   | $\pm 100$ | nA               |
| $\text{V}_{\text{GS(th)}}$ | Gate Threshold Voltage                    | $\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$  | 1.0 | 1.8 | 3.0       | V                |
| $\text{R}_{\text{DS(ON)}}$ | Drain-Source On-State Resistance          | $\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=1.5\text{A}$   | -   | 220 | 280       | $\text{m}\Omega$ |
|                            |   | $\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=1.5\text{A}$  |     | 230 | 300       | $\text{m}\Omega$ |
| $\text{G}_{\text{fs}}$     | Forward Transconductance                  | $\text{V}_{\text{DS}}=15\text{V}, \text{I}_D=1.5\text{A}$   | -   | 3   | -         | S                |
| $\text{C}_{\text{iss}}$    | Input Capacitance                         | $\text{V}_{\text{DS}}=25\text{V}, \text{V}_{\text{GS}}=0\text{V},$<br>$\text{F}=1.0\text{MHz}$  | -   | 235 | -         | PF               |
| $\text{C}_{\text{oss}}$    | Output Capacitance                        |   | -   | 36  | -         | PF               |
| $\text{C}_{\text{rss}}$    | Reverse Transfer Capacitance              |   | -   | 20  | -         | PF               |
| $\text{t}_{\text{d(on)}}$  | Turn-on Delay Time                        | $\text{V}_{\text{DD}}=75\text{V}, \text{I}_D=1\text{A}, \text{R}_L=75\Omega$<br>$\text{V}_{\text{GS}}=10\text{V}, \text{R}_G=6\Omega$ | -   | 8   | -         | nS               |
| $\text{t}_r$               | Turn-on Rise Time                         |   | -   | 10  | -         | nS               |
| $\text{t}_{\text{d(off)}}$ | Turn-Off Delay Time                       |   | -   | 20  | -         | nS               |
| $\text{t}_f$               | Turn-Off Fall Time                        |   | -   | 15  | -         | nS               |
| $\text{Q}_g$               | Total Gate Charge                         | $\text{V}_{\text{DS}}=75\text{V}, \text{I}_D=1.5\text{A},$<br>$\text{V}_{\text{GS}}=10\text{V}$                                       | -   | 8   | -         | nC               |
| $\text{Q}_{\text{gs}}$     | Gate-Source Charge                        |   | -   | 1.4 | -         | nC               |
| $\text{Q}_{\text{gd}}$     | Gate-Drain Charge                         |   | -   | 2.1 | -         | nC               |
| $\text{V}_{\text{SD}}$     | Diode Forward Voltage <sup>(Note 3)</sup> | $\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=2\text{A}$  | -   | -   | 1.2       | V                |
| $\text{I}_s$               | Diode Forward Current <sup>(Note 2)</sup> |   | -   | -   | 2         | A                |

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup>FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$
3. The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 4 . The data is theoretically the same as  $\text{I}_D$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

**150V N-Channel Enhancement Mode MOSFET**
**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs. Gate-Source**

**Fig.3 Forward Characteristics of Reverse**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

**150V N-Channel Enhancement Mode MOSFET**


**150V N-Channel Enhancement Mode MOSFET**
**Package Mechanical Data: SOT23**


| Symbol | Dimensions in Millimeters |       |
|--------|---------------------------|-------|
|        | MIN.                      | MAX.  |
| A      | 0.900                     | 1.150 |
| A1     | 0.000                     | 0.100 |
| A2     | 0.900                     | 1.050 |
| b      | 0.300                     | 0.500 |
| c      | 0.080                     | 0.150 |
| D      | 2.800                     | 3.000 |
| E      | 1.200                     | 1.400 |
| E1     | 2.250                     | 2.550 |
| e      | 0.950TYP                  |       |
| e1     | 1.800                     | 2.000 |
| L      | 0.550REF                  |       |
| L1     | 0.300                     | 0.500 |
| θ      | 0°                        | 8°    |